

Amendments to the claims (this listing replaces all prior versions):

1-28. (Canceled)

29. (Currently Amended) An apparatus comprising a piezoelectric element ~~including lead zirconium titanate~~, and a first thermoplastic bonding component ~~having a plurality of openings and a thickness between 1 micron and 150 microns, wherein the thermoplastic bonding component having a plurality of openings is heat-bonded to a surface of the piezoelectric element, wherein the apparatus is an ink jet printing module;~~

wherein the apparatus further comprises an ink channel, the piezoelectric element being positioned to subject ink within the channel to jetting pressure, and electrical contacts arranged for activation of the piezoelectric element; and

wherein the first thermoplastic bonding component covers the ink channel and includes a filter.

30-31. (Cancelled)

32. (Currently Amended) The apparatus of claim 29, wherein the piezoelectric element is comprises lead zirconium titanate.

33. (Currently Amended) The apparatus of claim 29, wherein the first thermoplastic bonding component has a thickness between 10 microns and 125 microns.

34. (Canceled)

35. (Currently Amended) The apparatus of claim 29, wherein the first thermoplastic bonding component has a thickness between 20 microns and 50 microns.

36. (Currently Amended) The apparatus of claim 29, wherein the first thermoplastic bonding component includes an adhesive polyimide.

37. (Canceled)

38. (Currently Amended) The apparatus of claim ~~37~~ 29, further comprising a series of channels.

39. (Previously Presented) The apparatus of claim 38, wherein each of said channels is covered by a single piezoelectric element.

40. (Canceled)

41. (Currently Amended) The apparatus of claim 29, wherein the filter including a repeating pattern of units having a plurality of openings and a land between each pair of adjacent ~~the~~ units is at least 50 microns.

42. (Previously Presented) The apparatus of claim 41, wherein the filter has a width of 300 to 495 microns.

43. (Previously Presented) The apparatus of claim 29, further comprising an orifice plate and a protector strip adhered to the orifice plate, wherein either the orifice plate or the protector strip includes a thermoplastic bonding material.

44. (Cancelled)

45. (Currently Amended) A method of manufacturing an ink jet printing module comprising:

contacting a first component of an ink jet printing module having a surface with a first thermoplastic bonding component; and

heating the surface to bond the surface to the first thermoplastic bonding component wherein the ink jet printing module includes an ink channel, a piezoelectric element being positioned to subject ink within the channel to jetting pressure, and electrical contacts arranged

for activation of the piezoelectric element and wherein the first thermoplastic bonding component is placed over the ink channel and includes a filter.

46. (Cancelled)

47. (Cancelled)

48. (Currently Amended) The method of claim 45 wherein the first thermoplastic bonding component includes a plurality of openings.

49. (Cancelled)

50. (Previously presented) The method of claim 45 wherein the filter includes a repeating pattern of units having a plurality of openings.

51. (Currently Amended) The method of claim 50, wherein a land between ~~the~~ each pair of adjacent units is at least 50 microns.

52. (Currently Amended) An ink jet printing module comprising:
a piezoelectric element having a surface;
a first thermoplastic bonding component including a filter;
a second thermoplastic bonding component heat-bonded to the surface;
an ink channel, the piezoelectric element being positioned to subject ink within the channel to jetting pressure; and
electrical contacts arranged for activation of the piezoelectric element,
wherein ~~the thermoplastic bonding component has a thickness between 10 microns and 125 microns and~~ the first thermoplastic bonding component covers the ink channel ~~and includes a filter.~~

53. (Canceled)

54. (Currently Amended) The ink jet printing module of claim 52, wherein the first thermoplastic bonding component has a thickness between 20 and 50 microns.

55. (Currently Amended) The ink jet printing module of claim 52, wherein the second thermoplastic bonding component includes a first surface heat-bonded to the surface of the piezoelectric element and a second surface heat-bonded to a surface of an ink jet printing module component.

56. (Currently Amended) The ink jet printing module of claim 52, wherein the second thermoplastic bonding component includes an electrode pattern.

57. (Currently Amended). The ink jet printing module of claim 52, wherein the piezoelectric element is comprises lead zirconium titanate.

58. (Currently Amended) The ink jet printing module of claim 52, wherein the first thermoplastic bonding component includes a polyimide.

59. (Canceled)

60. (Previously presented) The ink jet printing module of claim 52, further comprising a series of channels.

61. (Previously presented) The ink jet printing module of claim 60, wherein each of said channels is covered by a single piezoelectric element.

62. (Canceled)

63. (Currently Amended) The ink jet printing module of claim 52, wherein the filter includes a repeating pattern of units having a plurality of openings and a land between ~~the~~ each pair of adjacent units is at least 50 microns.

64. (Currently Amended) The ink jet printing module of claim 63, wherein the width of the filter is 300 to 495 microns.

65. (Previously presented) The ink jet printing module of claim 52, further comprising an orifice plate and a protector strip adhered to the orifice plate, wherein either the orifice plate or the protector strip includes a thermoplastic bonding material.

66-84. (Cancelled)

85. (Currently Amended) The method of claim 45, further comprising applying pressure to the surface and the first thermoplastic bonding component.

86. (Previously presented) The method of claim 85, wherein pressure is applied during heating.

87. (Currently Amended) The method of claim 45, wherein the surface and the first thermoplastic bonding component are substantially free of liquid adhesive.

88-91. (Cancelled)

92. (Currently Amended) The method of claim 45, wherein the first thermoplastic bonding component has a thickness between 1 micron and 150 microns.

93. (Currently Amended) The method of claim 45, wherein the first thermoplastic bonding component has a thickness between 10 micron and 125 microns.

94. (Currently Amended) The method of claim 45, wherein the first thermoplastic bonding component has a thickness between 20 microns and 50 microns.

95. (Currently Amended) The method of claim 45, wherein the first thermoplastic bonding component includes an adhesive polyimide.

96. (Previously presented) The method of claim 45, wherein the ink jet printing module includes a series of channels.

97. (Previously presented) The method of claim 45, wherein the module includes an orifice plate and the method further comprises adhering a protector strip over the orifice plate.

98. (Previously presented) The method of claim 97, wherein the orifice plate includes a thermoplastic bonding material adjacent to the protector strip.

99. (Previously presented) The method of claim 97, wherein the protector strip includes a thermoplastic bonding material adjacent to the orifice plate.

100-109. (Cancelled)

110. (New) The apparatus of claim 29, further comprising a second thermoplastic bonding component.

111. (New) The apparatus of claim 110, wherein the second thermoplastic bonding component includes a first surface heat-bonded to a surface of the piezoelectric element and a second surface heat-bonded to a surface of a component of the apparatus.

112. (New) The apparatus of claim 110, wherein the second thermoplastic bonding component includes an electrode pattern.

113. (New) The apparatus of claim 29, wherein the first thermoplastic bonding component has a thickness between 1 micron and 150 microns.

114. (New) The apparatus of claim 29, wherein the first thermoplastic bonding component includes a plurality of openings.

115. (New) The method of claim 45, further comprising providing a second thermoplastic bonding component.

